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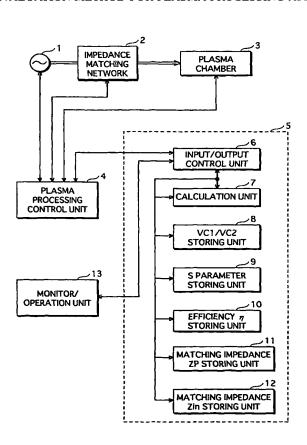
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(54) Title: PLASMA PROCESSING APPARATUS, CONTROL METHOD FOR PLASMA PROCESSING APPARATUS, AND EVALUATION METHOD FOR PLASMA PROCESSING APPARATUS



(57) Abstract: A plasma processing apparatus comprises: an RF generator operable to output RF power; an impedance matching network operable to receive the RF power; a plasma chamber operable to receive an output from the impedance matching network; a storing unit operable to store information relating to an S parameter of the impedance matching network; and a control unit operable to control an operating condition for the plasma chamber, based on the information relating to the S parameter.

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